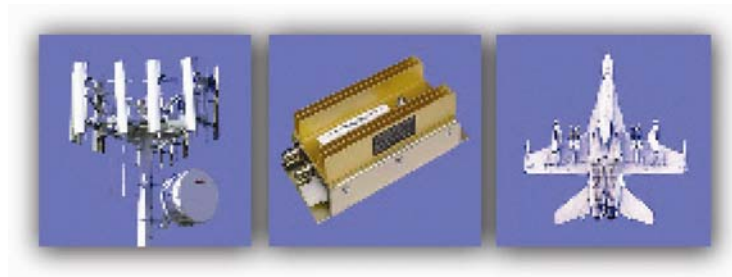




TRF-41/43/45

General Processing Guidelines



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Attention to handling :

- Do not use any mechanical scrubbing (including Pumice) during PCB fabrication;
- TRF-41/43/45 are relatively soft and thin than handling should be with great care;
- TRF-41/43/45 are PTFE laminate which requires Plasma for PTH pretreatment.

Drilling

1. Use new drill bits (Std 130o) within 800 hits , 1 panel per stack (max 2) ; Ft Pressure 40 psi ;
2. Use AI Entry on the top , and then ~1mm Phenolic board to cover PCB board ;
3. Use hi-pressure air gun to blow any leftover in drilled holes ;
4. Drilling parameters below as reference (the small the holes , the faster RPM , the smaller C/L)

Diameter (mm)	Speed (kRPM)	Infeed (IPM)	Retract (IPM)	Max Hit
0.35	85	132	400	1000
0.50	80	150	500	1000
0.70	60	153	500	1000
0.80	52	161	500	1000
1.05	40	173	500	1000
1.30	32	157	500	1000
1.60	26	133	500	1000
1.80	23	118	500	1000
2.50	20	80	500	1000

* Drill bit suppliers usually carry special drill/rout bits for PTFE board fabrication.

Plasma

Chemical clean might be needed after Plasma treatment to clean copper surface.

TRF-41/43/45 Plasma :

Step	O2 (%)	N2 (%)	CF4 (%)	H2 (%)	Pressure (Torr)	RF (W)	Seg time (min)	Flow (LT/min)
1	80	10	10	0	250	4200	15	2.50
2	0	20	0	80	250	4200	45	2.50

Check Plasma Action:

Use Dyne pen to check wettability.

Plasma action effect last about 8 hours.



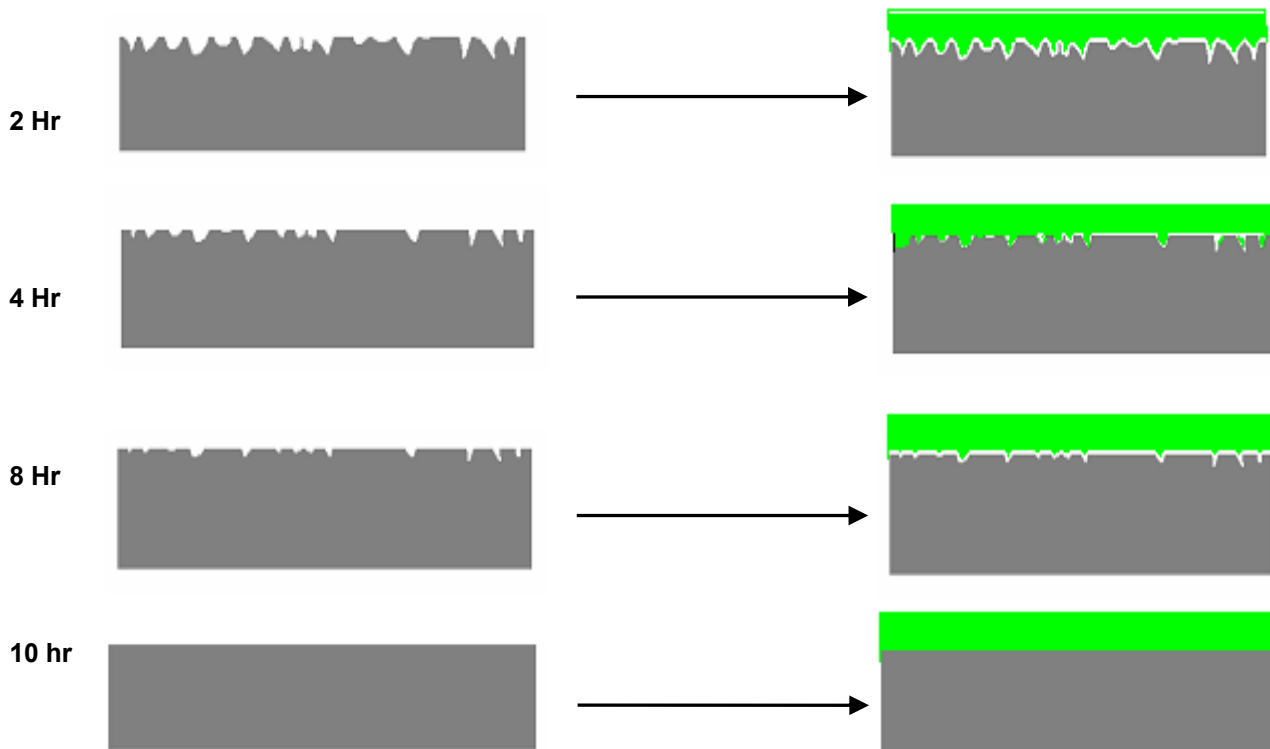
PTH :

1. No need to pass Desmearing process (KMnO4).
2. Starting PTH from microetch.

W/F Solder Resist :

Chemical cleaning → baking (90°C, 30min) → Ink screening → Prebaking (70°C, 36min) → Exposure → Developing → Final baking: 80°C、100°C、150°C, 30min each)

Ink screening should be within 8 hours after etching otherwise solder mask adhesion to PTFE surface might be weak that peeling off might happens.



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